



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-05-20
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KMQ7*L752UA6	A	SHENZHEN B/E	2015-05-20
Amount	UoM	Unit type	ST ECOPACK Grade	
150.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAuAg	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	9.85, 3.9, 1.52	16	GULL WING	
Comment	Package: SO 16 .15 TO JEDEC MS-012; MD valid for CP: SG2525AP, SG2525AP013TR.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KMQ7*L752UA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	4.192	mg	supplier	die	Silicon (Si)	7440-21-3		4.098	mg	977571	27313
				supplier	metallization	Aluminium (Al)	7429-90-5		0.052	mg	12408	347
				supplier	Passivation	Silicon Nitride	12033-89-5		0.018	mg	4295	120
				supplier	Passivation	Silicon Oxide	7631-86-9		0.024	mg	5727	160
Leadframe	Copper & its alloys	24.621	mg	supplier	alloy	Copper (Cu)	7440-50-8		23.671	mg	961415	157807
				supplier	alloy	Iron (Fe)	7439-89-6		0.557	mg	22623	3713
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.034	mg	1381	227
				supplier	alloy	Zinc (Zn)	7440-66-6		0.029	mg	1178	193
				supplier	metallization	Nickel (Ni)	7440-02-0		0.085	mg	3452	567
				supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	122	20
				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	122	20
Die attach	Other Organic Materials	1.472	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		1.339	mg	909647	8927
				supplier	glue or tape	acrylate	Proprietary		0.074	mg	50272	493
				supplier	glue or tape	Methacrylate	Proprietary		0.059	mg	40082	393
Bonding wires	Other inorganic materials	0.029	mg	supplier	wire	Copper (Cu)	7440-50-8		0.029	mg	1000000	193
Encapsulation	Other Organic Materials	119.686	mg	supplier	mold compound	Silica, vitreous	60676-86-0		104.965	mg	877003	699767
				supplier	mold compound	Epoxy resin	EC 413-900-7		4.787	mg	39996	31913
				supplier	mold compound	Epoxy	29690-82-2		4.787	mg	39996	31913
				supplier	mold compound	phenol resin	Proprietary		3.591	mg	30004	23940
				supplier	mold compound	additive	Proprietary		1.197	mg	10001	7980
				supplier	mold compound	carbon black	1333-86-4		0.359	mg	3000	2393